

#### **Automotive MOSFET**

#### OptiMOS™ 7 Power-Transistor







#### **Features**

- OptiMOS<sup>™</sup> power MOSFET for automotive applications
- N-channel Enhancement mode Normal Level
- Extended qualification beyond AEC-Q101
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- · RoHS compliant
- 100% Avalanche tested



General automotive applications.

#### **Product Validation**

Qualified for automotive applications. Product validation according to AEC-Q101.

### **Product Summary**

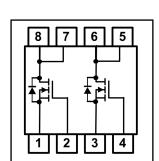
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$V_{\mathrm{DS}}$	40	V
R <sub>DS(on)</sub>	2.49	mΩ
I <sub>D</sub> (chip limited)	125	Α

Туре	Package	Marking

PG-TDSON-8-60





7N4N024D

## IAUCN04S7N024D



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# **Maximum Ratings**

at  $T_j = 25$ °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I <sub>D</sub>	$V_{GS} = 10 \text{ V}$ , Chip limitation <sup>1,2)</sup>	125	А
		V <sub>GS</sub> = 10 V, DC current	60	
		$T_a = 100^{\circ}\text{C}, V_{GS} = 10 \text{ V}, R_{thJA}$ on 2s2p <sup>2,3)</sup>	18	
Pulsed drain current <sup>2)</sup>	I <sub>D,pulse</sub>	$T_{\rm C}$ = 25°C, $t_{\rm p}$ = 100 $\mu$ s	325	
Avalanche energy, single pulse <sup>2)</sup>	E <sub>AS</sub>	I <sub>D</sub> = 30 A	60	mJ
Avalanche current, single pulse	I <sub>AS</sub>	-	60	Α
Gate source voltage	$V_{GS}$	-	±20	٧
Power dissipation	P <sub>tot</sub>	T <sub>C</sub> = 25°C	72	W
Operating and storage temperature	$T_{\rm j}, T_{\rm stg}$	-	-55 +175	°C

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# Thermal Characteristics<sup>2)</sup>

Parameter.	Symbol Conditions	Values				
Parameter	Symbol	Conditions	min.	typ.	max.	Unit
Thermal resistance, junction - case	$R_{thJC}$	-	_	_	2.1	K/W
Thermal resistance, junction - ambient <sup>3)</sup>	$R_{thJA}$	-	-	47	-	

## **Electrical Characteristics**

at T<sub>i</sub>=25 °C, unless otherwise specified

Parameter	S b l	Symbol Conditions –	Values			l	
	Symbol		min.	typ.	max.	Unit	
Static Characteristics							
Drain-source breakdown voltage	V <sub>(Br)DSS</sub>	$V_{GS} = 0 \text{ V},$ $I_D = 1 \text{ mA}$	40	-	-	V	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 25 \mu\text{A}$	2.2	2.6	3.0		
		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 25^{\circ}\text{C}$	-	_	1	μА	
Zero gate voltage drain current	/ <sub>DSS</sub>	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V},$ $T_j = 100^{\circ}\text{C}^{2}$	-	_	6		
Gate-source leakage current	I <sub>GSS</sub>	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	100	nA	
		$V_{GS} = 7 \text{ V}, I_D = 15 \text{ A}$	_	2.60	3.15	mΩ	
Drain-source on-state resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$	_	2.12	2.49		
Gate resistance <sup>2)</sup>	R <sub>G</sub>	-	_	2.5	_	Ω	





Parameter	Symbol Conditions	Values			11:4:4			
	Symbol	1 2 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	min.	typ.	max.	Unit		
Dynamic Characteristics <sup>2)</sup>	Dynamic Characteristics <sup>2)</sup>							
Input capacitance	C iss		_	1590	2067	pF		
Output capacitance	C oss	$V_{GS} = 0 \text{ V}, V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$	_	925	1203			
Reverse transfer capacitance	C <sub>rss</sub>		-	34	51			
Turn-on delay time	t <sub>d(on)</sub>		-	8	-	ns		
Rise time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, V_{GS} = 10 \text{ V},$ $I_{D} = 30 \text{ A}, R_{G} = 3.5 \Omega$	_	4	-			
Turn-off delay time	t <sub>d(off)</sub>		_	14	-			
Fall time	t <sub>f</sub>		_	6	_			

**Gate Charge Characteristics**2)

Gate to source charge	Q <sub>gs</sub>		ı	6.6	9	nC
Gate to drain charge	Q <sub>gd</sub>	$V_{\rm DD} = 20  \text{V}, I_{\rm D} = 30  \text{A},$	-	5	8	
Gate charge total	Qg	$V_{DD} = 20 \text{ V}, I_D = 30 \text{ A},$ $V_{GS} = 0 \text{ to } 10 \text{ V}$	-	23	30	
Gate plateau voltage	V <sub>plateau</sub>		-	4.1	-	V

#### **Reverse Diode**

Diode continuous forward current <sup>2)</sup>	Is	T <sub>C</sub> = 25°C	ı	ı	60	А
Diode pulse current <sup>2)</sup>	I <sub>S,pulse</sub>	$T_{\rm C} = 25^{\circ}{\rm C}, t_{\rm p} = 100 \mu{\rm s}$	ı	ı	325	
Diode forward voltage	V <sub>SD</sub>	$V_{GS} = 0 \text{ V}, I_F = 30 \text{ A}, T_j = 25^{\circ}\text{C}$	ı	0.8	0.95	V
Reverse recovery time <sup>2)</sup>	t <sub>rr</sub>	V <sub>R</sub> = 20 V, I <sub>F</sub> = 50 A	-	24	36	ns
Reverse recovery charge <sup>2)</sup>	Q <sub>rr</sub>	$di_F/dt = 100 A/\mu s$	ı	9	18	nC

 $<sup>^{1)}</sup>$  Practically the current is limited by the overall system design including the customer-specific PCB.

<sup>&</sup>lt;sup>2)</sup> The parameter is not subject to production testing – specified by design.

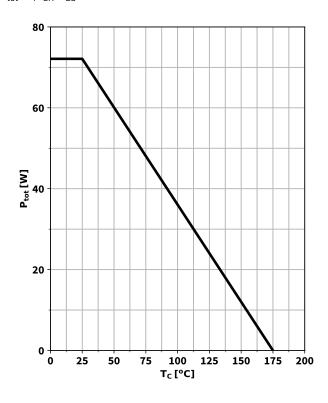
<sup>&</sup>lt;sup>3)</sup> Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.



## **Electrical characteristics diagrams**

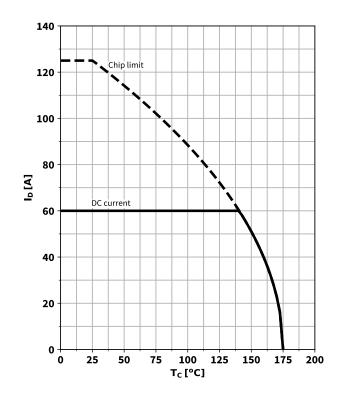
#### 1 Power dissipation

 $P_{\text{tot}} = f(T_{\text{C}}); V_{\text{GS}} \ge 6 \text{ V}$ 



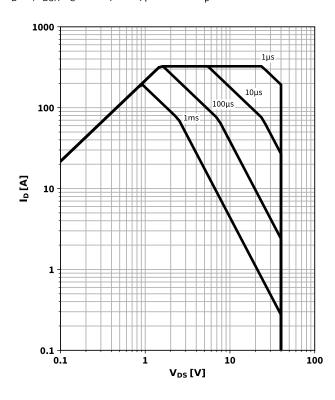
#### 2 Drain current

 $I_{\text{D}} = f(T_{\text{C}}); V_{\text{GS}} \ge 6 \text{ V}$ 



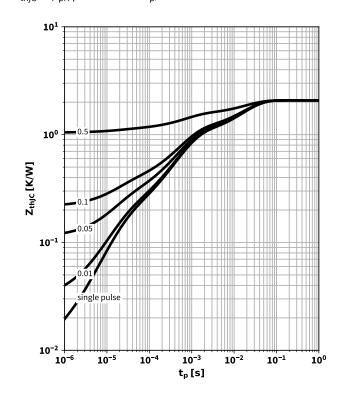
#### 3 Safe operating area

 $I_{\rm D}$  = f( $V_{\rm DS}$ );  $T_{\rm C}$  = 25 °C; D = 0; parameter:  $t_{\rm p}$ 



#### 4 Max. transient thermal impedance

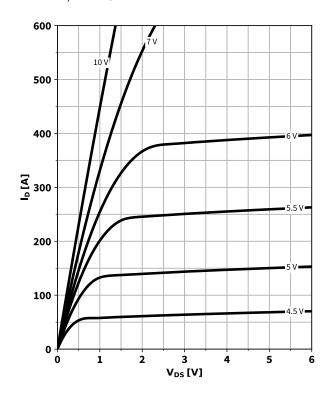
 $Z_{\text{thJC}} = f(t_p)$ ; parameter: D =  $t_p/T$ 





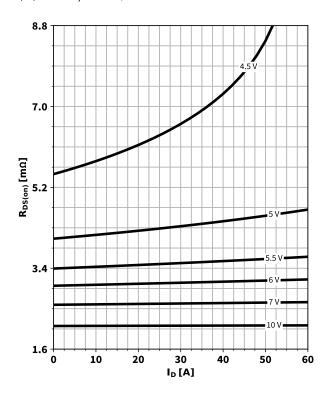
#### 5 Typ. output characteristics

 $I_D = f(V_{DS}); T_j = 25 \,^{\circ}\text{C}; \text{ parameter: } V_{GS}$ 



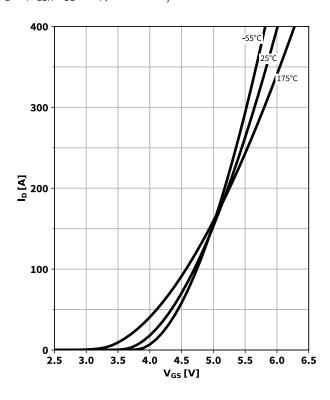
#### 6 Typ. drain-source on-state resistance

 $R_{\mathrm{DS(on)}} = \mathrm{f}(I_{\mathrm{D}}); T_{\mathrm{j}} = 25 \, ^{\circ}\mathrm{C}; \mathrm{parameter}: V_{\mathrm{GS}}$ 



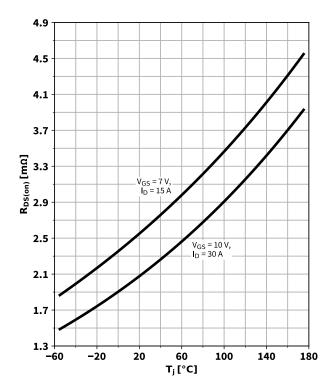
#### 7 Typ. transfer characteristics

 $I_D = f(V_{GS}); V_{DS} = 6 \text{ V}; \text{ parameter: } T_j$ 



#### 8 Typ. drain-source on-state resistance

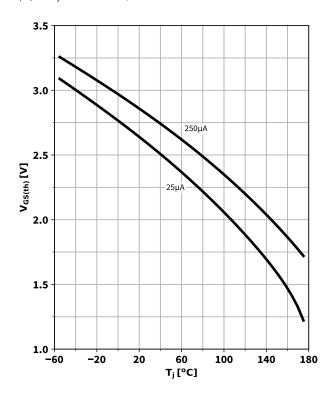
 $R_{DS(on)} = f(T_j)$ ; parameter:  $I_D$ ,  $V_{GS}$ 





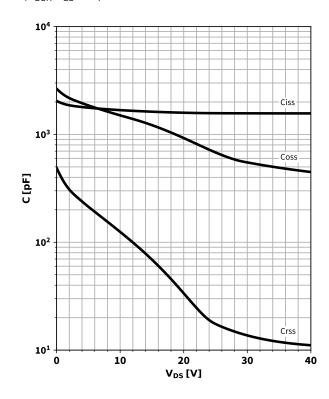
#### 9 Typ. gate threshold voltage

 $V_{\text{GS(th)}} = f(T_{\text{j}}); V_{\text{GS}} = V_{\text{DS}}; \text{ parameter: } I_{\text{D}}$ 



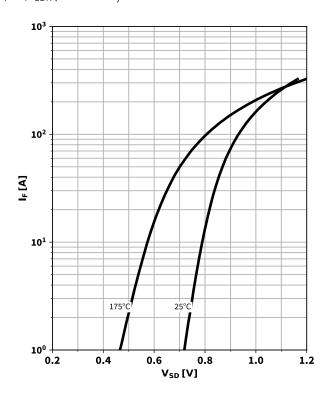
#### 10 Typ. capacitances

 $C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$ 



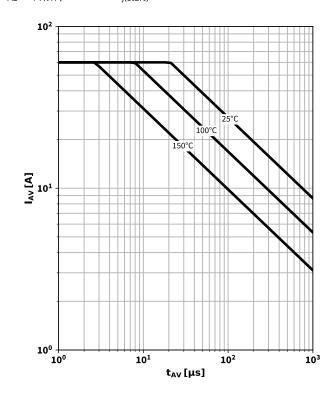
#### 11 Typ. forward diode characteristics

 $I_F = f(V_{SD})$ ; parameter:  $T_j$ 



#### 12 Typ. avalanche characteristics

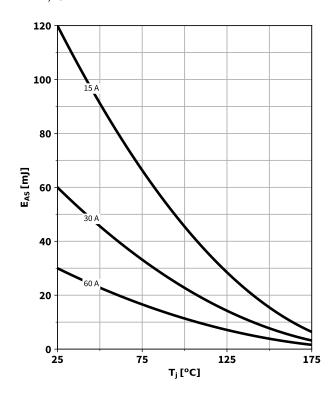
 $I_{AS} = f(t_{AV})$ ; parameter:  $T_{j(start)}$ 





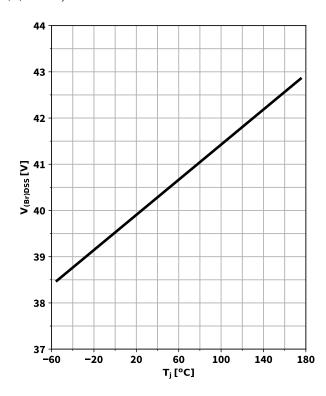
#### 13 Typical avalanche energy

 $E_{AS} = f(T_j)$ ; parameter:  $I_D$ 



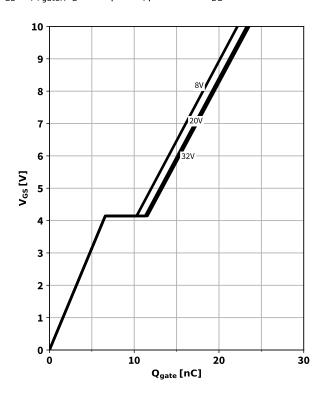
#### 14 Drain-source breakdown voltage

 $V_{(Br)DSS} = f(T_j); I_D = 1 \text{ mA}$ 

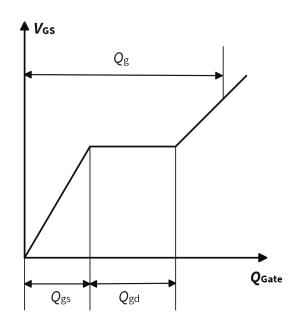


#### 15 Typ. gate charge

 $V_{GS} = f(Q_{gate}); I_D = 30 \text{ A pulsed}; parameter: } V_{DD}$ 



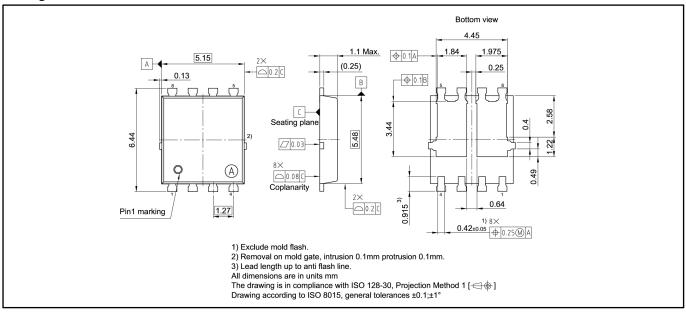
#### 16 Gate charge waveforms



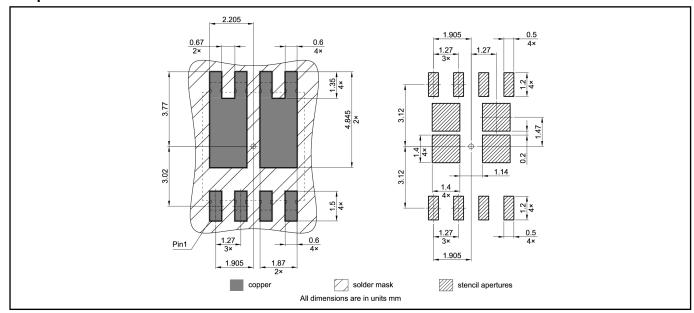
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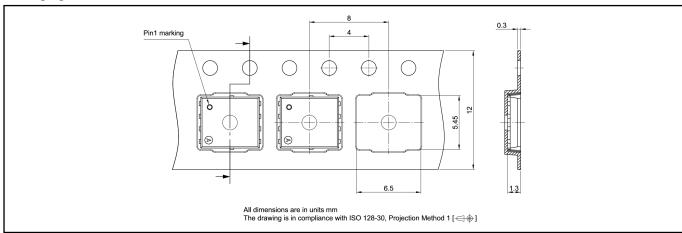
#### **Package Outline**



#### **Footprint**



#### **Packaging**



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# **Revision History**

Revision	Date Changes			
Revision 1.0	2024-10-04	Final Data Sheet		

#### Trademarks

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